FAIRCHILD SEMICONDUCTOR TM

July 1996

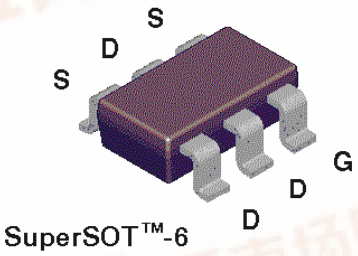
NDC631N
N-Channel Logic Level Enhancement Mode Field Effect Transistor

General Description

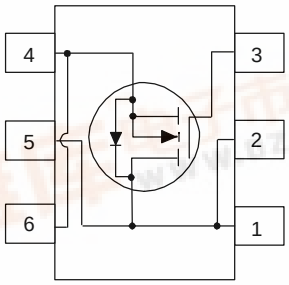
These N-Channel logic level enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is tailored to minimize on-state resistance. These devices are particularly suited for low voltage applications in notebook computers, portable phones, PCMICA cards, and other battery powered circuits where fast switching, and low in-line power loss are needed in a very small outline surface mount package.

Features

- 4.1 A, 20 V. $R_{DS(ON)}$ = 0.06 Ω @ V_{GS} = 4.5 V
  $R_{DS(ON)}$ = 0.075 Ω @ V_{GS} =2.7 V.
- Proprietary SuperSOT™-6 package design using copper lead frame for superior thermal and electrical capabilities.
- High density cell design for extremely low $R_{DS(ON)}$.
- Exceptional on-resistance and maximum DC current capability.



SuperSOT™-6



Absolute Maximum Ratings T_A = 25°C unless otherwise note

Symbol	Parameter		NDC631N	Units
V_{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage - Continuous		8	V
I_D	Drain Current - Continuous	(Note 1a)	4.1	A
	- Pulsed		15	
P_D	Maximum Power Dissipation	(Note 1a)	1.6	W
		(Note 1b)	1	
		(Note 1c)	0.8	
T_J,T_{STG}	Operating and Storage Temperature Range		-55 to 150	°C
THERMAL CHARACTERISTICS				
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	30	°C/W

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Conditions		Min	Typ	Max	Units
OFF CHARACTERISTICS							
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 µA		20			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 16 V, V_{GS} = 0 V				1	µA
			T_J = 55°C			10	µA
I_{GSSF}	Gate - Body Leakage, Forward	V_{GS} = 8 V, V_{DS} = 0 V				100	nA
I_{GSSR}	Gate - Body Leakage, Reverse	V_{GS} = -8 V, V_{DS} = 0 V				-100	nA
ON CHARACTERISTICS (Note 2)							
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 µA		0.4	0.7	1	V
			T_J = 125°C	0.3	0.5	0.8	
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS} = 4.5 V, I_D = 4.1 A			0.039	0.06	Ω
			T_J = 125°C		0.06	0.11	
		V_{GS} = 2.7 V, I_D = 3.6 A			0.05	0.075	
$I_{D(on)}$	On-State Drain Current	V_{GS} = 4.5 V, V_{DS} = 5 V		15			A
g_{FS}	Forward Transconductance	V_{DS} = 4.5 V, I_D = 4.1 A			12		S
DYNAMIC CHARACTERISTICS							
C_{iss}	Input Capacitance	V_{DS} = 10 V, V_{GS} = 0 V, f = 1.0 MHz			365		pF
C_{oss}	Output Capacitance				230		pF
C_{rss}	Reverse Transfer Capacitance				95		pF
SWITCHING CHARACTERISTICS (Note 2)							
$t_{D(on)}$	Turn - On Delay Time	V_{DD} = 5 V, I_D = 1 A, V_{GEN} = 4.5 V, R_{GEN} = 6 Ω			9	17	ns
t_r	Turn - On Rise Time				25	45	ns
$t_{D(off)}$	Turn - Off Delay Time				28	50	ns
t_f	Turn - Off Fall Time				8	15	ns
Q_g	Total Gate Charge	V_{DS} = 10 V, I_D = 4.1 A, V_{GS} = 4.5 V			10	14	nC
Q_{gs}	Gate-Source Charge				1		nC
Q_{gd}	Gate-Drain Charge				3.3		nC

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
DRAIN-SOURCE DIODE CHARACTERISTICS						
I_S	Continuous Source Diode Current				1.3	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 1.3 A (Note 2)		0.75	1.2	V

Notes:

1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

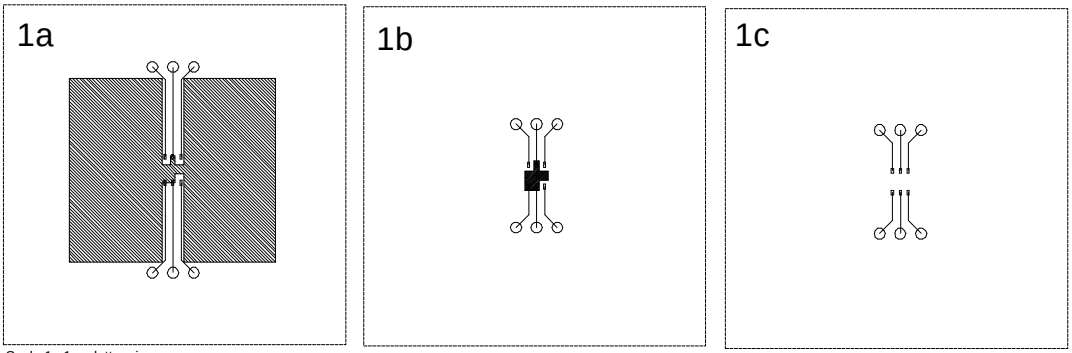
$$P_D(t) = \frac{T_J - T_A}{R_{\theta JA}(t)} = \frac{T_J - T_A}{R_{\theta JC} + R_{\theta CA}(t)} = I_D^2(t) \times R_{DS(ON)@T_J}$$

Typical $R_{\theta JA}$ using the board layouts shown below on 4.5"x5" FR-4 PCB in a still air environment:

a. 78°C/W when mounted on a 1 in^2 pad of 2oz copper.

b. 125°C/W when mounted on a 0.01 in^2 pad of 2oz copper.

c. 156°C/W when mounted on a 0.003 in^2 pad of 2oz copper.



Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%.

Typical Electrical Characteristics

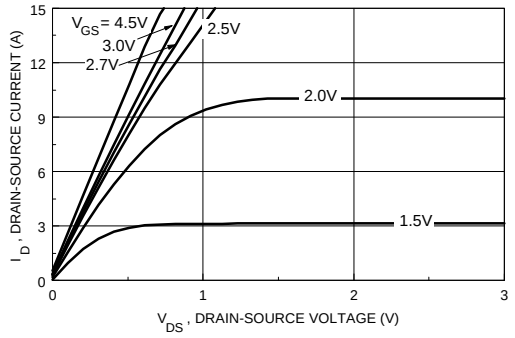


Figure 1. On-Region Characteristics.

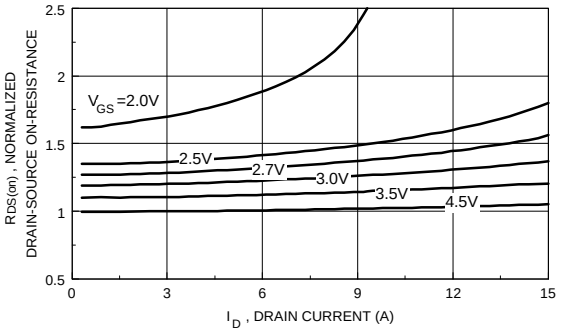


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

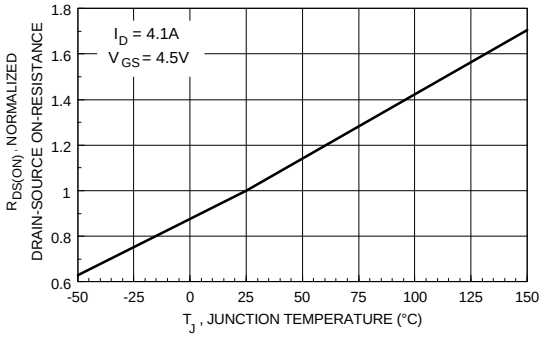


Figure 3. On-Resistance Variation with Temperature.

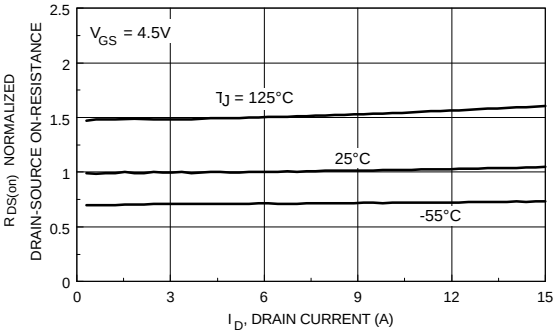


Figure 4. On-Resistance Variation with Drain Current and Temperature.

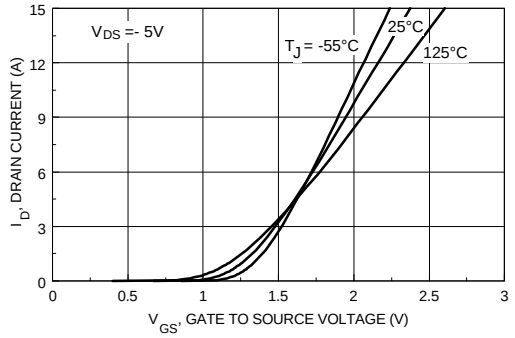


Figure 5. Transfer Characteristics.

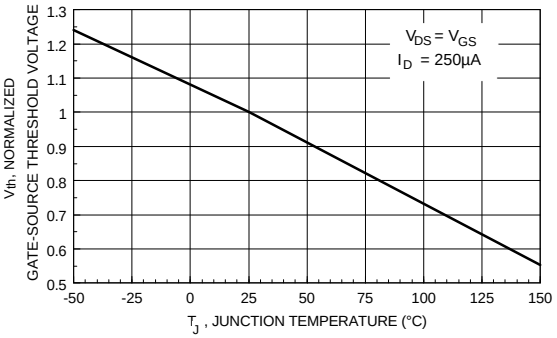


Figure 6. Gate Threshold Variation with Temperature.

Typical Electrical Characteristics (continued)

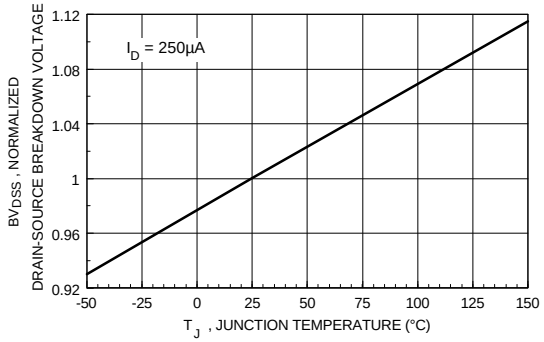


Figure 7. Breakdown Voltage Variation with Temperature.

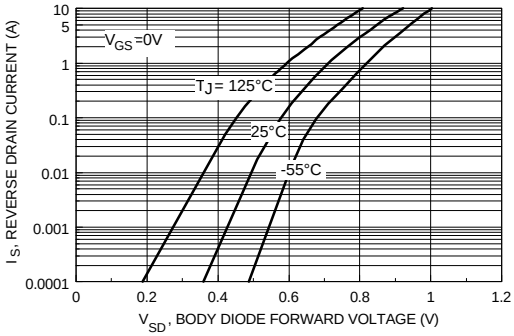


Figure 8. Body Diode Forward Voltage Variation with Source Current and Temperature.

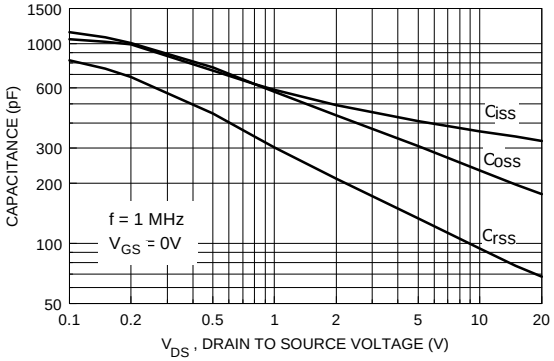


Figure 9. Capacitance Characteristics.

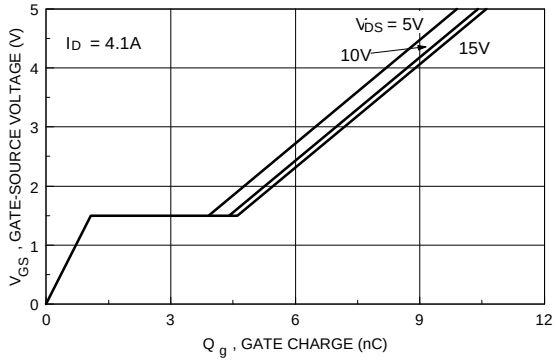


Figure 10. Gate Charge Characteristics.

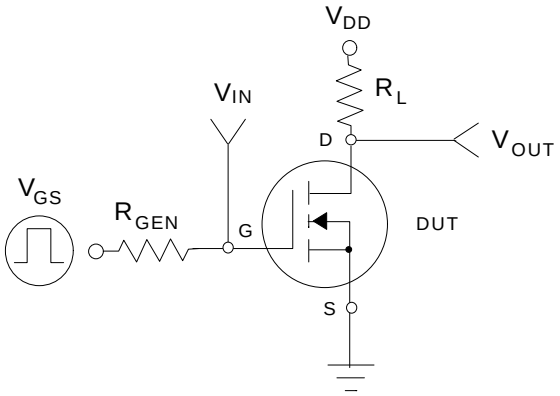


Figure 11. Switching Test Circuit.

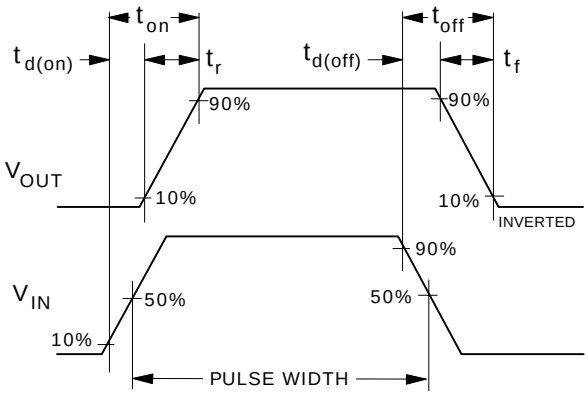


Figure 12. Switching Waveforms.

Typical Electrical and Thermal Characteristics (continued)

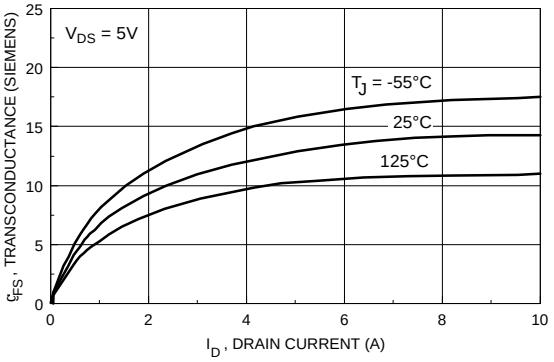


Figure 13. Transconductance Variation with Drain Current and Temperature.

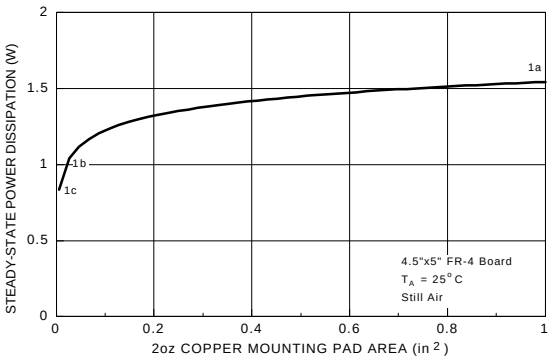


Figure 14. SuperSOT™-6 Maximum Steady-State Power Dissipation versus Copper Mounting Pad Area.

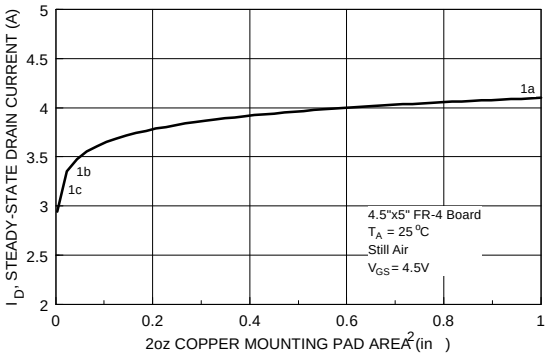


Figure 15. Maximum Steady-State Drain Current versus Copper Mounting Pad Area.

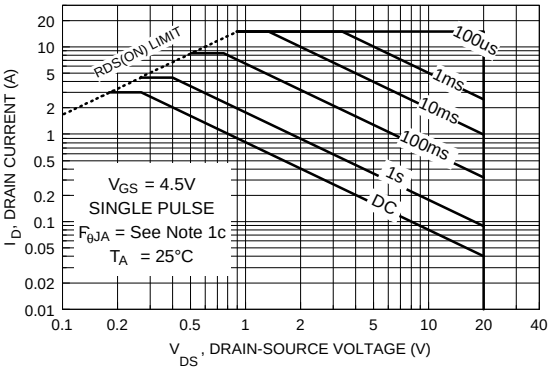


Figure 16. Maximum Safe Operating Area.

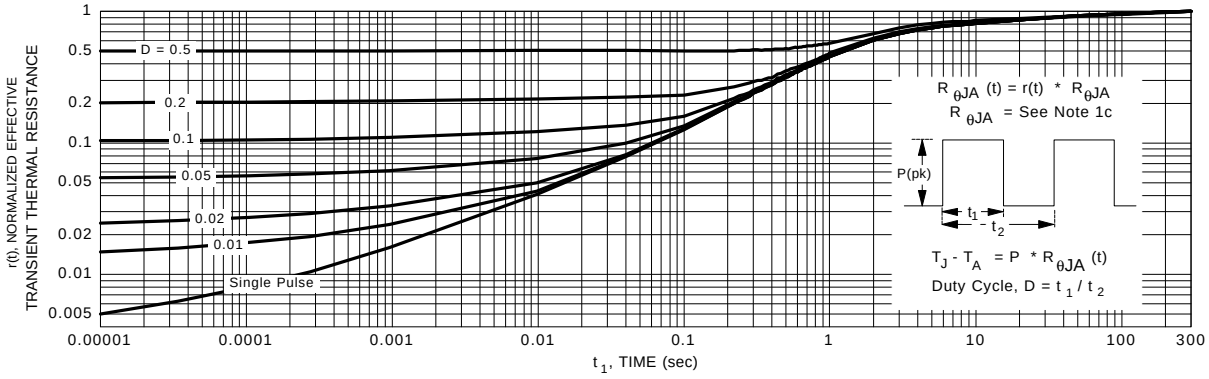


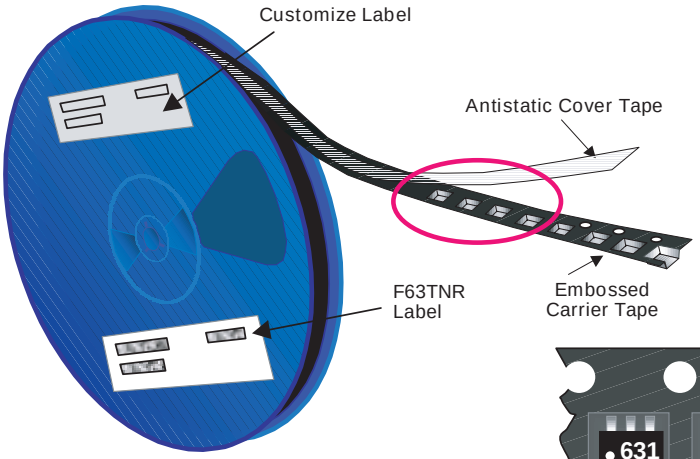
Figure 17. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1c. Transient thermal response will change depending on the circuit board design.

SuperSOT™-6 Tape and Reel Data and Package Dimensions

FAIRCHILD SEMICONDUCTOR™

SSOT-6 Packaging Configuration: Figure 1.0

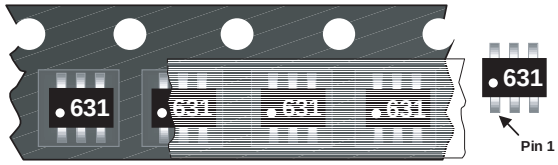


Packaging Description:

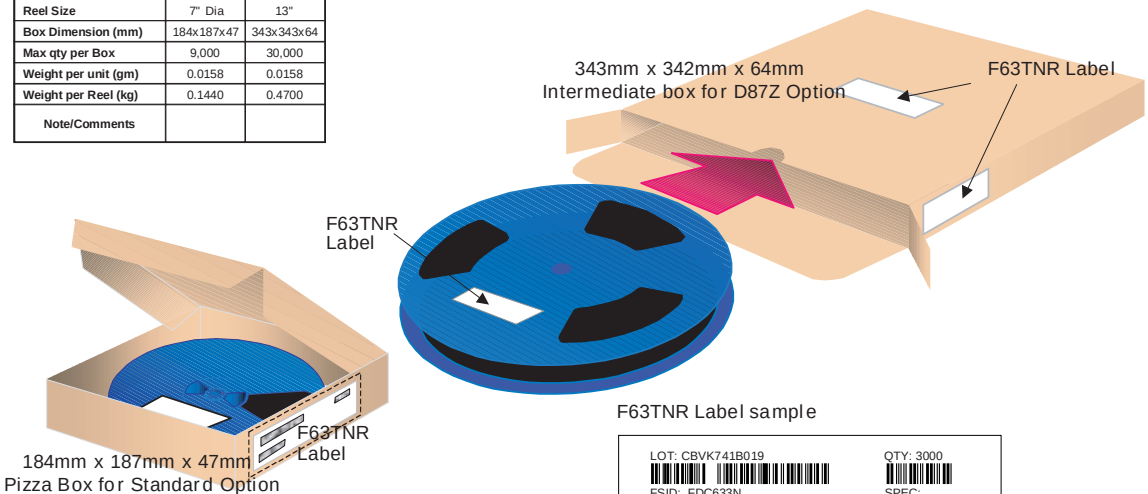
SSOT-6 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table.

These full reels are individually barcode labeled and placed inside a pizza box (illustrated in figure 1.0) made of recyclable corrugated brown paper with a Fairchild logo printing. One pizza box contains three reels maximum. And these pizza boxes are placed inside a barcode labeled shipping box which comes in different sizes depending on the number of parts shipped.

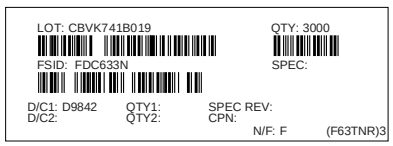
SSOT-6 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	184x187x47	343x343x64
Max qty per Box	9,000	30,000
Weight per unit (gm)	0.0158	0.0158
Weight per Reel (kg)	0.1440	0.4700
Note/Comments		



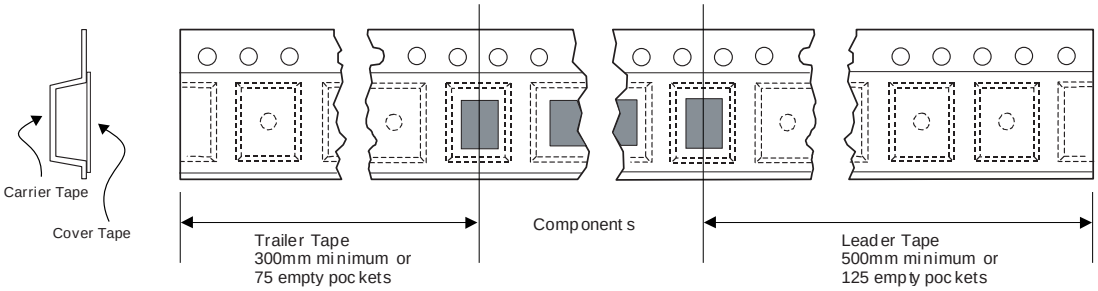
SSOT-6 Unit Orientation



F63TNR Label sample



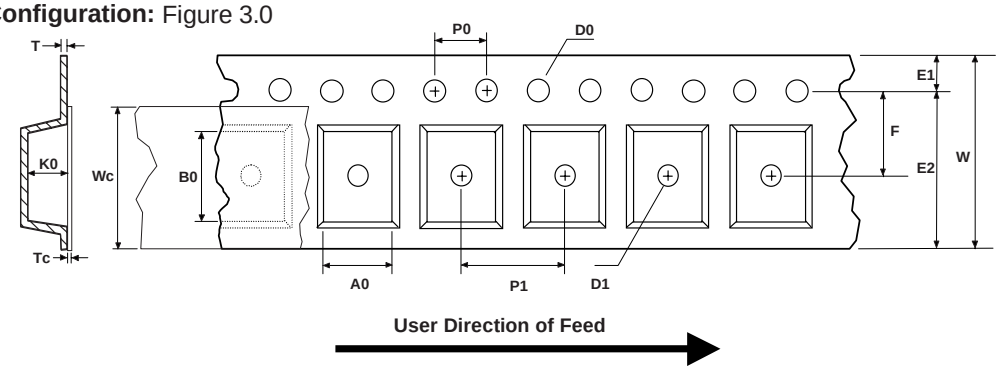
SSOT-6 Tape Leader and Trailer Configuration: Figure 2.0



SuperSOT™-6 Tape and Reel Data and Package Dimensions, continued

SSOT-6 Embossed Carrier Tape

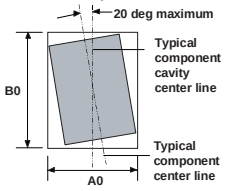
Configuration: Figure 3.0



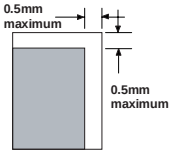
Dimensions are in millimeter														
Pkg type	**A0**	**B0**	**W**	**D0**	**D1**	**E1**	**E2**	**F**	**P1**	**P0**	**K0**	**T**	**Wc**	**Tc**
SSOT-6 (8mm)	3.23 +/-0.10	3.18 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.37 +/-0.10	0.255 +/-0.150	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).

Sketch A (Side or Front Sectional View)
Component Rotation

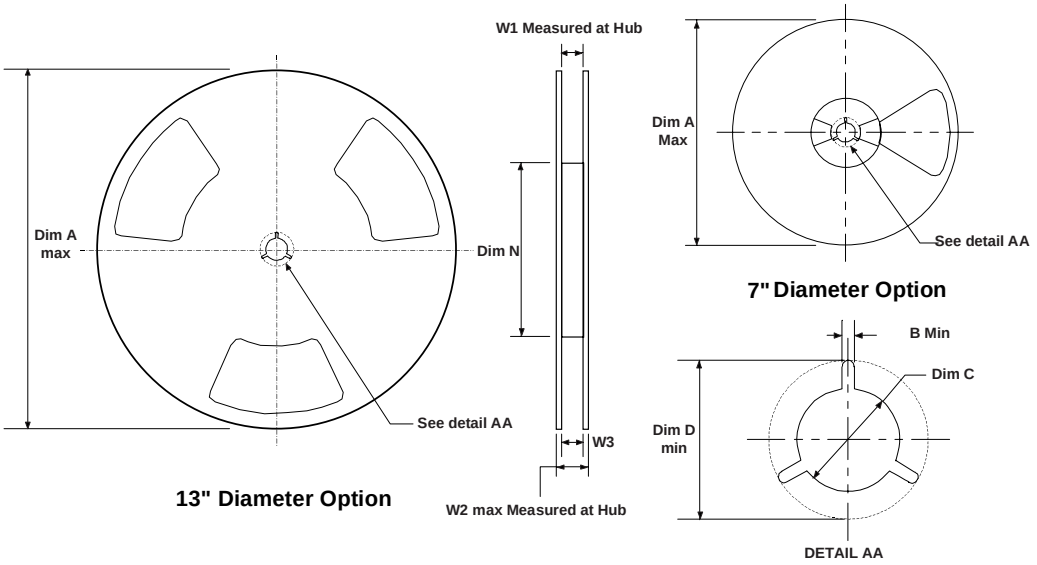


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

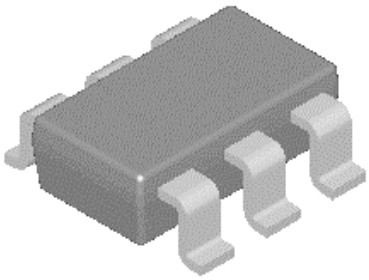
SSOT-6 Reel Configuration: Figure 4.0

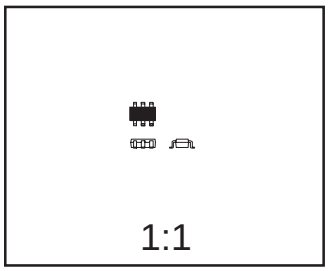


Dimensions are in inches and millimeters									
Tape Size	**Reel Option**	**Dim A**	**Dim B**	**Dim C**	**Dim D**	**Dim N**	**Dim W1**	**Dim W2**	**Dim W3 (LSL-USL)**
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9

SuperSOT™-6 Tape and Reel Data and Package Dimensions, continued

SuperSOT -6 (FS PKG Code 31, 33)

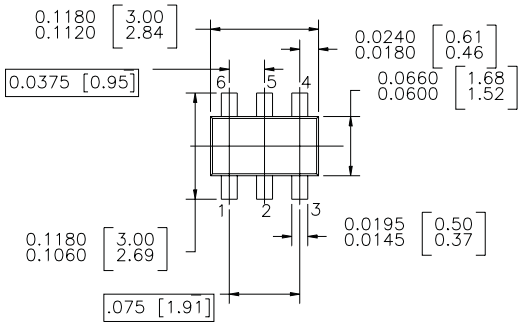


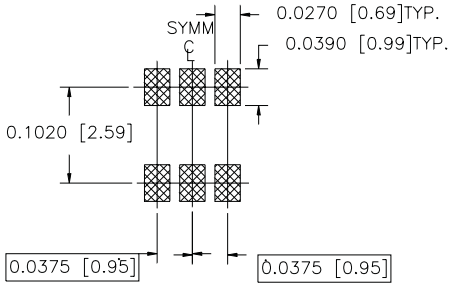


Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

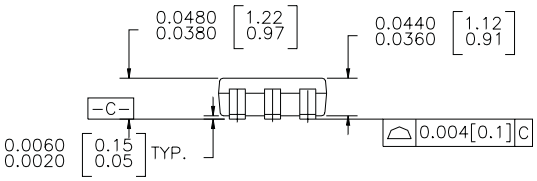
Part Weight per unit (gram): 0.0158

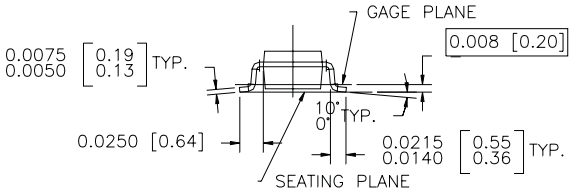




LAND PATTERN RECOMMENDATION

CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS





NOTES : UNLESS OTHERWISE SPECIFIED

1.0 STANDARD LEAD FINISH : 150 MICROINCHES 93.81 MICROMETERS)
MINIMUM TIN / LEAD (SOLDER) ON COPPER.

2.0 NO JEDEC REGISTRATION AS OF JULY 1996

SUPER SOT 6 LEADS

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As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.